

POLISHING HEAD, AND POLISHING TREATMENT DEVICE

ABSTRACT

To provide a polishing head and a polishing treatment device that can prevent uneven polishing, such as partial insufficient polishing or over-polishing, of a polished surface of a substrate, improve ESFQR or the like of the substrate surface, and steadily perform a polishing treatment of a large number of substrates with high quality.

The polishing head includes a head housing that has a first flange part that extends outward from an upper position of a circumferential surface of a cylindrical body and a second flange part that extends outward from a lower position of the circumferential surface, a membrane support ring that is sized to surround an outer circumference of the second flange part and has a third flange part that is formed at an upper end part thereof and located between the first flange part and the second flange part, a membrane that covers a lower end-side opening part of the membrane support ring and holds the wafer with a backing film pasted to a front surface thereof interposed therebetween, a retainer ring formed in a shape to surround an outer circumference of the substrate, and driving means that integrally horizontally rotates the head housing, the membrane support ring, and the retainer ring.

(Fig. 2)